

Electronic Filing System (EFS) Data Electronic Patent Application Submission USPTO Use Only

REINFORCED DIE PAD SUPPORT

EFS ID:

53067

Application ID:

10669820

Title of Invention:

STRUCTURE

First Named Inventor:

Chung Tzu

Domestic/Foreign Application:

Domestic Application

Filing Date:

2003-09-24

Effective Receipt Date:

2004-01-02

Submission Type:

Information Disclosure

Statement

Filing Type:

Confirmation number:

5197

Attorney Docket Number:

AMKOR090A

Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark

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Certificate Message Digest: deef0c4735f2097debece8d95d06caf1d9e2ca98



TRANSMITTAL

RADENIA Stylesheet Version v1.1.0

Title of Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number:

10/669820

Date:

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First Named Applicant:

Chung Hsing Tzu

Confirmation Number:

5197

Attorney Docket Number: AMKOR090A

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Mark B. Garred Registered Number: 34,823	/mbg/	Attorney

Documents being submitted

Files

us-ids

ids3-usidst.xml

us-ids.dtd

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Comments



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Ælectronic Version v18 Stylesheet Version v18.0

> Title of Invention

REINFORCED DIE PAD SUPPORT STRUCTURE

Application Number:

10/669820

5197

Confirmation Number: First Named Applicant:

Chung Tzu

Attorney Docket Number: AMKOR090A

Art Unit:

2811

Search string:

(5640047 or 5641997 or 5643433 or 5644169 or 5646831 or 5650663 or 5661088 or 5665996 or 5673479 or 5683806 or 5689135 or 5696666 or 5701034 or 5703407 or 5710064 or 5723899 or 5724233 or 5736432 or 5745984 or 5753532 or 5753977 or 5766972 or 5770888 or 5776798 or 5783861 or 5801440 or 5814877 or 5814881 or 5814883 or 5814884 or 5817540 or 5818105 or 5821457 or 5821615 or 5834830 or 5835988 or 5844306 or 5856911 or 5859471 or 5866939 or 5871782 or 5874784 or 5877043 or 5886397 or 5886398 or 5894108 or 5897339 or 5900676

or 5903049 or 5903050).pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date